

SEAM-20-02.0-S-10-2-A-K-TR SEAM-30-02.0-S-08-2-A-K-TR SEAM-30-03.5-S-04-2-A-K-TR

(1.27 mm) .050"

SEAM SERIES

HIGH-SPEED/HIGH-DENSITY OPEN-PIN-FIEL

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAM

Insulator Material: **Contact Material:** Copper Alloy
Operating Temp Range: -55 °C to +125 °C Current Rating (7 mm stack height): 2.7 A per pin (10 adjacent pins powered)

Plating: Au or Šn over 50 μ" (1.27 μm) Ni Working Voltage:

240 VA RoHS Compliant: Yes (-2 Solder type only) Lead-Free Solderable:

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



STANDARDS

- VITA 47
- VITA 57.1 FMC
- VITA 57.4 FMC+
- VITA 74 VNX
- PISMO™ 2

SEAM

STYLE

-02.0

-03.0

-03.5

-06.5

-07.0

-09.0

-11.0

Visit www.samtec.com/standards for more information.

-05.0

7 mm

8 mm

8.5 mm

11.5 mn

12 mm

14 mm

16 mm

Class 3 solder joint.

Some sizes, styles and options are non-standard,

MATED HEIGHTS

-06.0

8 mm

9 mm

9.5 mm

12.5 mm

13 mm

15 mm

17 mm

IPC-A-610F & IPC-J-STD-001F

SEAF LEAD STYLE

-06.5

8.5 mm

9.5 mm

10 mm

13 mm

13.5 mm

15.5 mm

-07.5

9.5 mm

10.5 mm

11 mm

14 mm

14.5 mm

Up to 500 Pins Mates with: SEAF, SEAFP (1.12 mm) .044" NOMINAL Standoffs: WIPE Low insertion/ Solder extraction charges forces HIGH-SPEED CHANNEL PERFORMANCE PAM4 SEAF/SEAM @ 10 mm Mated Stack Height Rating based on Samtec reference channel. **OTHER SOLUTIONS** For full SI performance data visit Samtec.com

Up to 560 pins

-04

=Four Rows

(-06.5 not

available)

-05

=Five Rows

(-06.5 not

available)

-06

=Six Rows

(-06.5 not

available)

-08

=Eight Rows

-10

=Ten Rows

Α

(5.61) .221

(6.60) .260 (7.11) .280

(10.16) .400

-07.0 (10.59) .417

-09.0 (12.60) .496

-11.0 (14.61) .575

LEAD

STYLE

-02.0

-03.0

-03.5

-06.5

10, –15, –20 30, –40, –50

SEAM

or contact SIG@samtec.com

NO. PINS

PER ROW

NO. OF

(-10 only available in 04 row) (-15 is only available in 4 Row with -02.0 lead style and 10 row with any lead style)

ĹEAD **STYLE** from chart

LEAD

STYLE

_1 = 10 µ" (0.25 µm) Gold on contact area, Matte Tin on solder tail

PLATING

OPTION

-S = 30 µ" (0.76 µm) Gold on contact area,

-04(7.06) .278 Matte Tin on -05. -06 (9.60) .378 solder tail -08(12.14) .478 -10 (14.68) .578 .050 ₽V No. of positions x (1.27) .050 + (4.98) .196.040

В

16.5 mm 17.5 mm 18.5 mn 050 a a a a a a a a a a a (0.86)(1.12) (1.02) DIA No. of positions x (1.27) .050 + (3.58) .141

NO. OF **SOLDER** ROWS TYPE

= Tin/Lead Alloy Solder Charge

–2 Lead-Free Solder Charge

(Required. Arrays will not self-center on solder pads)

= Alignment Pins

= Polyimide film Pick & Place Pad

> –TR =Tape & Reel

> > –FR

= Full Reel Tape & Reel Packaging (Must order max. quantities per reel. Contact Samtec for parts per reel)

POWER/SIGNAL APPLICATION



two-piece power/signal solutions

Due to technical progress, all designs, specifications and components are subject to change without notice

non-returnable.